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STTH10002

Ultrafast recovery diode

Datasheet – production data

Features

- Very low forward losses
- Low recovery time
- High surge current capability
- Insulated package
 - Insulating voltage = 2500 V rms
 - Capacitance = 45 pF
- Complies with UL standards (File ref: E81734)

Description

The STTH10002 is a dual rectifier suited for welding equipment, and high power industrial applications.

Packaged in ISOTOP, this device is intended for use in the secondary rectification of power converters.

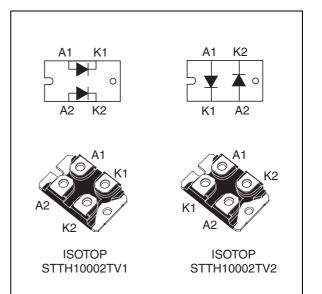


Table 1. Device summary

	-
I _{F(AV)}	2 x 50 A
V _{RRM}	200 V
T _j (max)	150 °C
V _F (typ)	0.72 V
t _{rr} (typ)	30 ns

This is information on a product in full production.

1 Characteristics

Table 2. Absolute ratings (limiting values at $T_j = 25$ °C, unless otherwise specified)

Symbol	Parameter			Unit
V _{RRM}	Repetitive peak reverse voltage		200	V
I _{F(RMS)}	Forward rms current Per diode		150	А
	Average forward current $S = 0.5$	Per diode $T_c = 100 \ ^{\circ}C$		А
^I F(AV)	$I_{F(AV)}$ Average forward current, $\delta = 0.5$	Per device $T_c = 95 \ ^{\circ}C$		A
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$		750	А
T _{stg}	Storage temperature range			°C
Тj	Maximum operating junction temperature			°C

Table 3.Thermal parameters

Symbol	Parameter		Value	Unit
D	lupation to appo	Per diode	1	
R _{th(j-c)} Junction to case	Total	0.55	°C/W	
R _{th(c)}	Coupling		0.1	

When the two diodes 1 and 2 are used simultaneously:

 Δ Tj(diode 1) = P (diode 1) X R_{th(i-c)} (Per diode) + P (diode 2) x R_{th(c)}

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
	Povorco lookago ourront	T _j = 25 °C	$V_{R} = V_{RRM}$	-	-	50	μA
'R`´	IR ⁽¹⁾ Reverse leakage current	T _j = 125 °C		-	50	500	
	T 05 %C	I _F = 50 A	-	-	1		
	V _F ⁽²⁾ Forward voltage drop	T _j = 25 °C	I _F = 100 A	-	-	1.15	
V _F ⁽²⁾		T _j = 125 °C	I _F = 100 A	-	0.90	1.0	V
	T 150.00	I _F = 50 A	-	0.72	0.80		
	T _j = 150 °C	I _F = 100 A	-	0.86	0.97		

1. Pulse test: $t_p = 5 \text{ ms}, \delta < 2\%$

2. Pulse test: t_p = 380 µs, δ < 2%

To evaluate the conduction losses use the following equation: P = 0.63 x $I_{F(AV)}$ + 0.0034 ${I_F}^2_{(RMS)}$



Table 5.Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{rr} Reverse recovery time		$ \begin{array}{l} I_F = 1 \hspace{0.1 cm} A, \hspace{0.1 cm} dI_F/dt = -50 \hspace{0.1 cm} A/\mu s, \\ V_R = 30 \hspace{0.1 cm} V, \hspace{0.1 cm} T_j = 25 \hspace{0.1 cm} ^{\circ} C \end{array} $	-	53	65	ns
		$\label{eq:lf} \begin{array}{l} I_{F} = 1 \ A, \ dI_{F}/dt = -200 \ A/\mus, \\ V_{R} = 30 \ V, \ T_{j} = 25 \ ^{\circ}C \end{array}$	-	30	37	
I _{RM}	Reverse recovery current	I_F = 50 A, dI_F/dt = 200 A/µs, V_R = 160 V, T_j = 125 °C	-	10	13	А
t _{fr}	Forward recovery time	I_F = 50 A, dI_F/dt = 200 A/µs V_{FR} = 1.1 x $V_{Fmax},$ T_j = 25 $^\circ\text{C}$	-	180	-	ns
V _{FP}	Forward recovery voltage	$I_F = 50 \text{ A}, \text{ d}I_F/\text{d}t = 200 \text{ A}/\mu\text{s},$ $T_j = 25 ^\circ\text{C}$	-	1.6	-	V



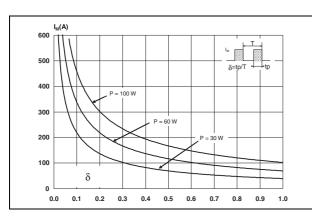


Figure 3. Forward voltage drop versus forward current (maximum values, per diode)

Figure 2. Forward voltage drop versus forward current (typical values, per diode)

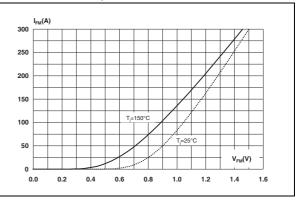


Figure 4. Relative variation of thermal impedance, junction to case, versus pulse duration

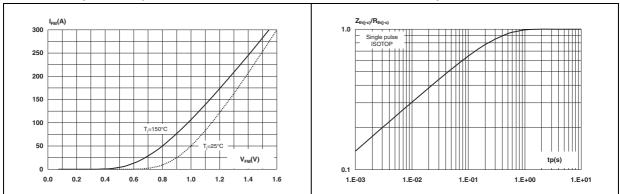
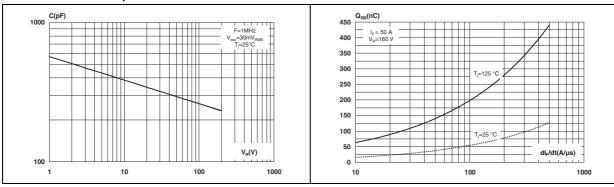
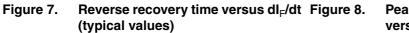


Figure 5. Junction capacitance versus reverse applied voltage (typical values)

Figure 6. Reverse recovery charges versus dl_F/dt (typical values)





Peak reverse recovery current versus dl_F/dt (typical values)

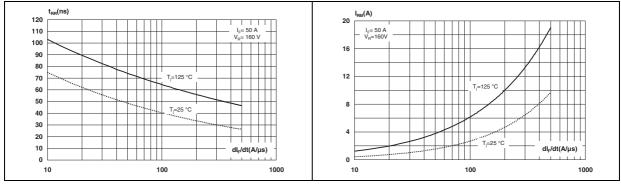
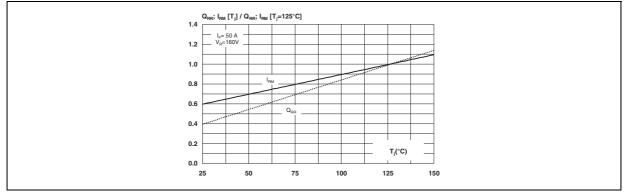


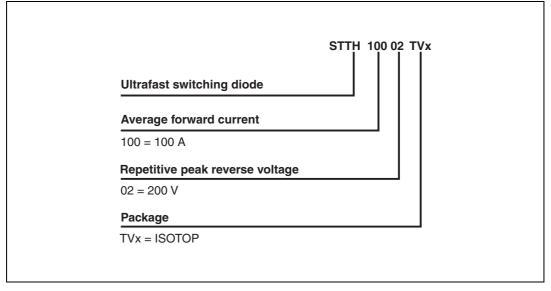
Figure 9. Dynamic parameters versus junction temperature





2 Ordering information scheme





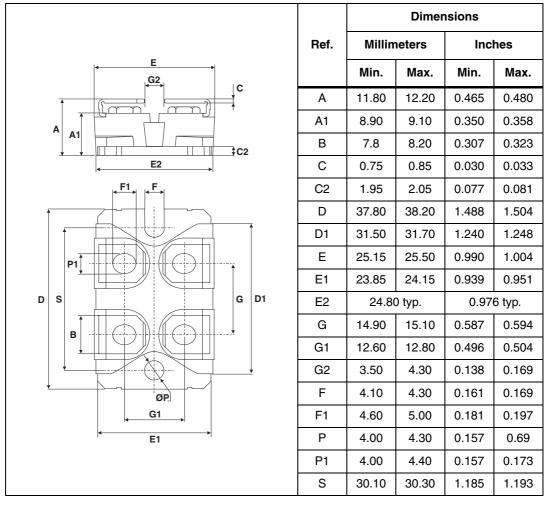


3 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.

Table 6. ISOTOP dimensions



4 Ordering information

Table 7.Ordering information

Order code	Marking	Package	Weight	Base qty ⁽¹⁾	Delivery mode
STTH10002TV1	STTH10002TV1	ISOTOP	27 g	10	Tube
STTH10002TV2	STTH10002TV2	130105	27 y	with screws	Tube

1. This product is supplied with 40 terminal screws and washers for each tube. The screws and washers are supplied in a separate pack with the order.

5 Revision history

	Table 8.	Document	revision	history
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Date	Revision	Changes
05-Apr-2006	1	First issue
23-Oct-2012	2	Added UL file reference. Updated storage temperature range in <i>Table 2</i> . Added footnote to <i>Table 7</i> .



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